

# Kai Zhu

## List of Publications by Year in descending order

Source: <https://exaly.com/author-pdf/6505398/publications.pdf>

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4  
papers

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citations

2258059

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2272923

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docs citations

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#	ARTICLE	IF	CITATIONS
1	Enhancing adhesion performance of sputtering Ti/Cu film on pretreated composite prepreg for stacking structure of IC substrates. <i>Composites Part B: Engineering</i> , 2019, 158, 400-405.	12.0	27
2	Convection-Dependent Competitive Adsorption between SPS and EO/PO on Copper Surface for Accelerating Trench Filling. <i>Journal of the Electrochemical Society</i> , 2019, 166, D93-D98.	2.9	14
3	Communication—Localized Accelerator Pre-Adsorption to Speed Up Copper Electroplating Microvia Filling. <i>Journal of the Electrochemical Society</i> , 2019, 166, D467-D469.	2.9	3
4	Anisotropic growth of electroless nickel–phosphorus plating on fine sliver lines for L-shape terminal electrode structure of chip inductor. <i>Applied Surface Science</i> , 2019, 496, 143633.	6.1	2